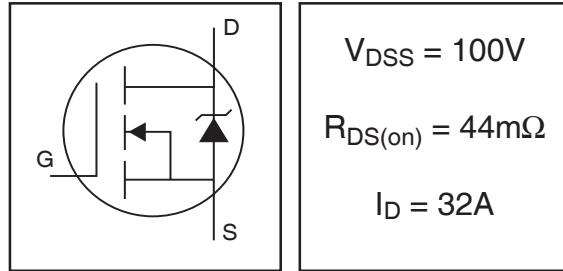


- Advanced Process Technology
- Ultra Low On-Resistance
- Dynamic dv/dt Rating
- 175°C Operating Temperature
- Fast Switching
- Fully Avalanche Rated
- Lead-Free

# IRFR3411PbF

# IRFU3411PbF

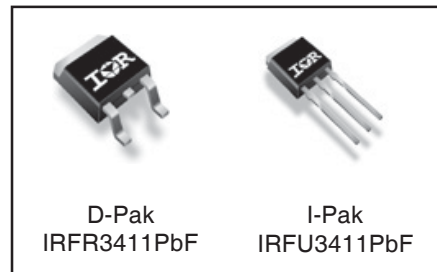
HEXFET® Power MOSFET



### Description

Advanced HEXFET® Power MOSFETs from International Rectifier utilize advanced processing techniques to achieve extremely low on-resistance per silicon area. This benefit, combined with the fast switching speed and ruggedized device design that HEXFET power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in a wide variety of applications.

The D-Pak is designed for surface mounting using vapor phase, infrared, or wave soldering techniques. The straight lead, I-Pak, version (IRFU series) is for through-hole mounting applications. Power dissipation levels up to 1.5 watts are possible in typical surface mount applications.



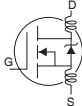
### Absolute Maximum Ratings

|                                 | Parameter                                       | Max.         | Units |
|---------------------------------|---|--------------|-------|
| $I_D @ T_C = 25^\circ\text{C}$  | Continuous Drain Current, $V_{GS} @ 10\text{V}$ | 32           | A     |
| $I_D @ T_C = 100^\circ\text{C}$ | Continuous Drain Current, $V_{GS} @ 10\text{V}$ | 23           |       |
| $I_{DM}$                        | Pulsed Drain Current ①                          | 110          |       |
| $P_D @ T_C = 25^\circ\text{C}$  | Power Dissipation                               | 130          | W     |
|                                 | Linear Derating Factor                          | 0.83         | W/°C  |
| $V_{GS}$                        | Gate-to-Source Voltage                          | $\pm 20$     | V     |
| $I_{AR}$                        | Avalanche Current ①                             | 16           | A     |
| $E_{AR}$                        | Repetitive Avalanche Energy ①                   | 13           | mJ    |
| dv/dt                           | Peak Diode Recovery dv/dt ③                     | 7.0          | V/ns  |
| $T_J$                           | Operating Junction and                          | -55 to + 175 | °C    |
| $T_{STG}$                       | Storage Temperature Range                       |              |       |
|                                 | Soldering Temperature, for 10 seconds           |              |       |

### Thermal Resistance

|                 | Parameter                        | Typ. | Max. | Units |
|-----------------|----------------------------------|------|------|-------|
| $R_{\theta JC}$ | Junction-to-Case                 | —    | 1.2  | °C/W  |
| $R_{\theta JA}$ | Junction-to-Ambient (PCB mount)* | —    | 50   |       |
| $R_{\theta JA}$ | Junction-to-Ambient              | —    | 110  |       |

## Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)

|  | Parameter                            | Min. | Typ. | Max. | Units | Conditions   |
|--|--------------------------------------|------|------|------|-------|--|
| V <sub>(BR)DSS</sub>                   | Drain-to-Source Breakdown Voltage    | 100  | —    | —    | V     | V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA   |
| ΔV <sub>(BR)DSS</sub> /ΔT <sub>J</sub> | Breakdown Voltage Temp. Coefficient  | —    | 0.12 | —    | V/°C  | Reference to 25°C, I <sub>D</sub> = 1mA  |
| R <sub>DS(on)</sub>                    | Static Drain-to-Source On-Resistance | —    | 36   | 44   | mΩ    | V <sub>GS</sub> = 10V, I <sub>D</sub> = 16A ④  |
| V <sub>GS(th)</sub>                    | Gate Threshold Voltage               | 2.0  | —    | 4.0  | V     | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA                           |
| g <sub>fs</sub>                        | Forward Transconductance             | 21   | —    | —    | S     | V <sub>DS</sub> = 50V, I <sub>D</sub> = 16A④   |
| I <sub>DSS</sub>                       | Drain-to-Source Leakage Current      | —    | —    | 25   | μA    | V <sub>DS</sub> = 100V, V <sub>GS</sub> = 0V   |
|  |                                      | —    | —    | 250  |       | V <sub>DS</sub> = 80V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 150°C                  |
| I <sub>GSS</sub>                       | Gate-to-Source Forward Leakage       | —    | —    | 100  | nA    | V <sub>GS</sub> = 20V  |
|  | Gate-to-Source Reverse Leakage       | —    | —    | -100 |       | V <sub>GS</sub> = -20V   |
| Q <sub>g</sub>                         | Total Gate Charge                    | —    | 48   | 71   | nC    | I <sub>D</sub> = 16A   |
| Q <sub>gs</sub>                        | Gate-to-Source Charge                | —    | 9.0  | 14   |       | V <sub>DS</sub> = 80V  |
| Q <sub>gd</sub>                        | Gate-to-Drain ("Miller") Charge      | —    | 14   | 21   |       | V <sub>GS</sub> = 10V, See Fig. 6 and 13   |
| t <sub>d(on)</sub>                     | Turn-On Delay Time                   | —    | 11   | —    | ns    | V <sub>DD</sub> = 50V  |
| t <sub>r</sub>                         | Rise Time                            | —    | 35   | —    |       | I <sub>D</sub> = 16A   |
| t <sub>d(off)</sub>                    | Turn-Off Delay Time                  | —    | 39   | —    |       | R <sub>G</sub> = 5.1Ω  |
| t <sub>f</sub>                         | Fall Time                            | —    | 35   | —    |       | V <sub>GS</sub> = 10V, See Fig. 10 ④   |
| L <sub>D</sub>                         | Internal Drain Inductance            | —    | 4.5  | —    | nH    | Between lead,<br>6mm (0.25in.)<br>from package<br>and center of die contact          |
| L <sub>S</sub>                         | Internal Source Inductance           | —    | 7.5  | —    |       |  |
| C <sub>iss</sub>                       | Input Capacitance                    | —    | 1960 | —    | pF    | V <sub>GS</sub> = 0V   |
| C <sub>oss</sub>                       | Output Capacitance                   | —    | 250  | —    |       | V <sub>DS</sub> = 25V  |
| C <sub>rss</sub>                       | Reverse Transfer Capacitance         | —    | 40   | —    |       | f = 1.0MHz, See Fig. 5   |
| E <sub>AS</sub>                        | Single Pulse Avalanche Energy②       | —    | 700③ | 185⑥ |       | I <sub>AS</sub> = 16A, L = 1.5mH   |

## Source-Drain Ratings and Characteristics

|                 | Parameter                                 | Min.   | Typ. | Max. | Units | Conditions  |
|-----------------|---|--|------|------|-------|---|
| I <sub>S</sub>  | Continuous Source Current<br>(Body Diode) | —  | —    | 33   | A     | MOSFET symbol<br>showing the<br>integral reverse<br>p-n junction diode. |
| I <sub>SM</sub> | Pulsed Source Current<br>(Body Diode)①    | —  | —    | 110  |       |   |
| V <sub>SD</sub> | Diode Forward Voltage                     | —  | —    | 1.2  | V     | T <sub>J</sub> = 25°C, I <sub>S</sub> = 16A, V <sub>GS</sub> = 0V ④     |
| t <sub>rr</sub> | Reverse Recovery Time                     | —  | 115  | 170  | ns    | T <sub>J</sub> = 25°C, I <sub>F</sub> = 16A                             |
| Q <sub>rr</sub> | Reverse Recovery Charge                   | —  | 505  | 760  | nC    | di/dt = 100A/μs ④   |
| t <sub>on</sub> | Forward Turn-On Time                      | Intrinsic turn-on time is negligible (turn-on is dominated by L <sub>S</sub> +L <sub>D</sub> ) |      |      |       |   |

### Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)
- ② Starting T<sub>J</sub> = 25°C, L = 1.5mH  
R<sub>G</sub> = 25Ω, I<sub>AS</sub> = 16A. (See Figure 12)
- ③ I<sub>SD</sub> ≤ 16A, di/dt ≤ 340A/μs, V<sub>DD</sub> ≤ V<sub>(BR)DSS</sub>,  
T<sub>J</sub> ≤ 175°C.
- ④ Pulse width ≤ 400μs; duty cycle ≤ 2%.

⑤ This is a typical value at device destruction and represents operation outside rated limits.

⑥ This is a calculated value limited to T<sub>J</sub> = 175°C .

\* When mounted on 1" square PCB (FR-4 or G-10 Material). For recommended footprint dering techniques refer to application note #AN-994.

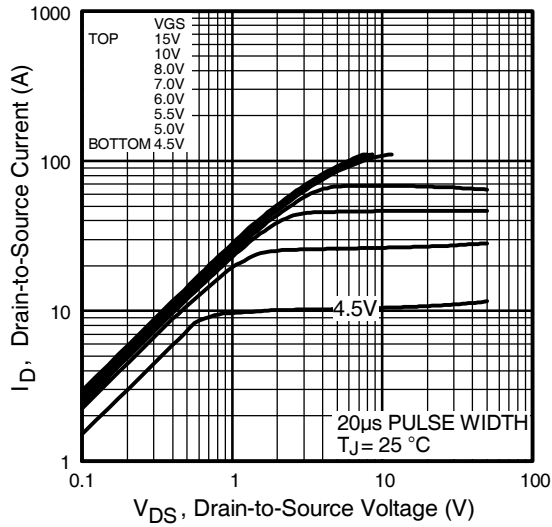


Fig 1. Typical Output Characteristics

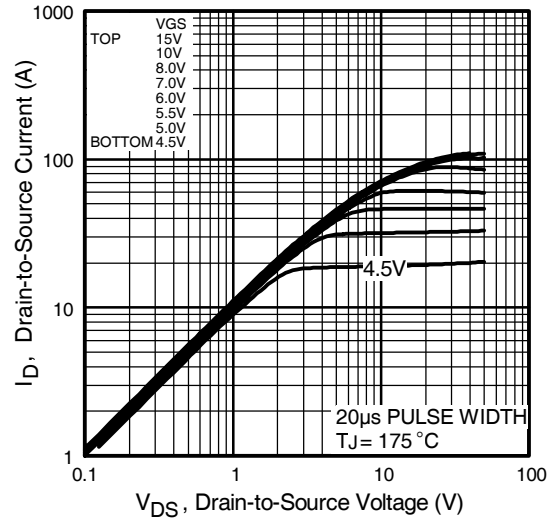


Fig 2. Typical Output Characteristics

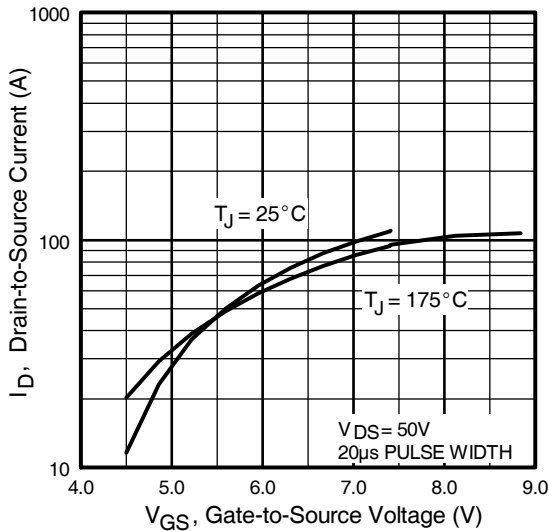


Fig 3. Typical Transfer Characteristics

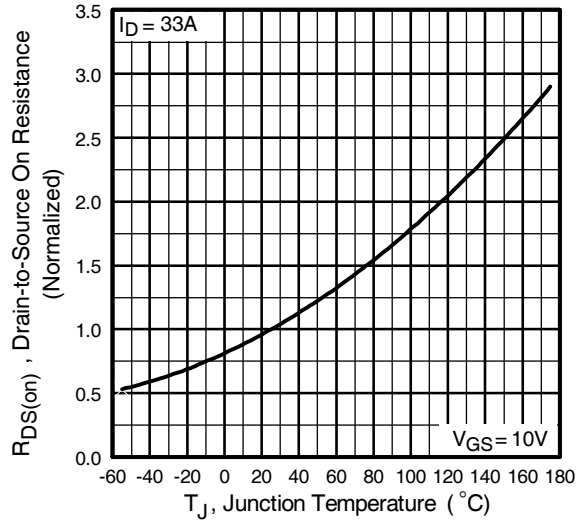
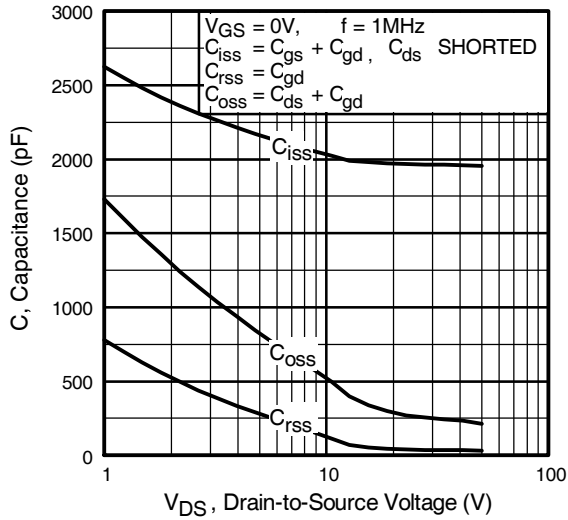
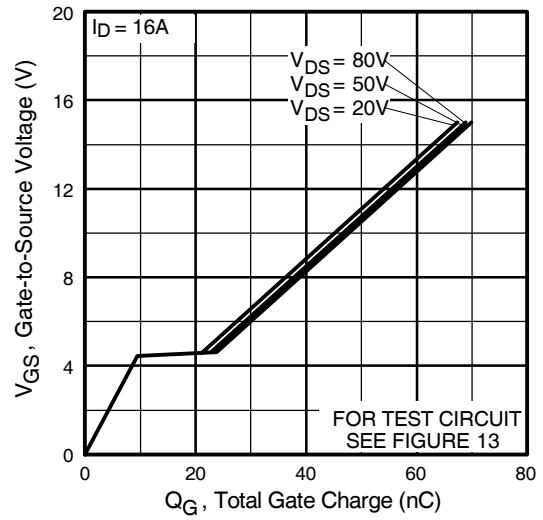


Fig 4. Normalized On-Resistance Vs. Temperature

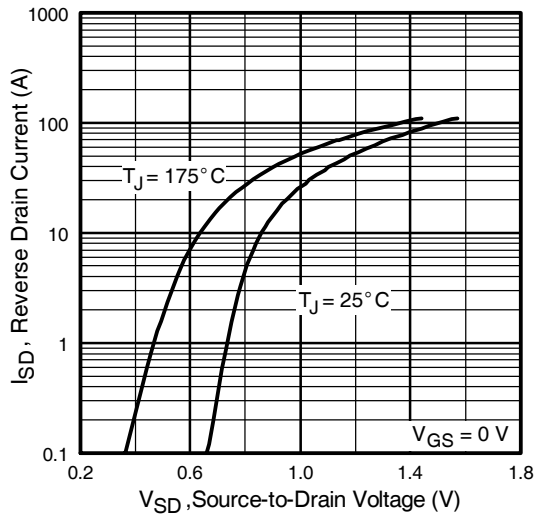
# IRFR/U3411PbF



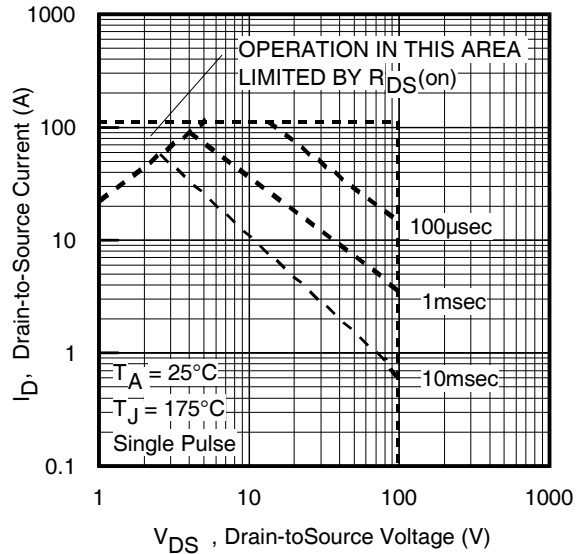
**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage



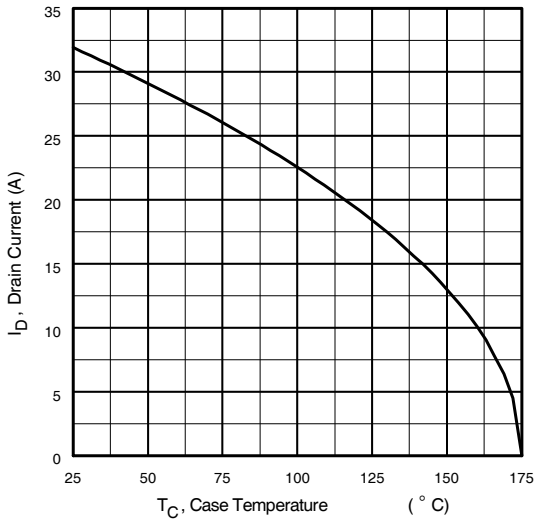
**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage



**Fig 7.** Typical Source-Drain Diode Forward Voltage



**Fig 8.** Maximum Safe Operating Area



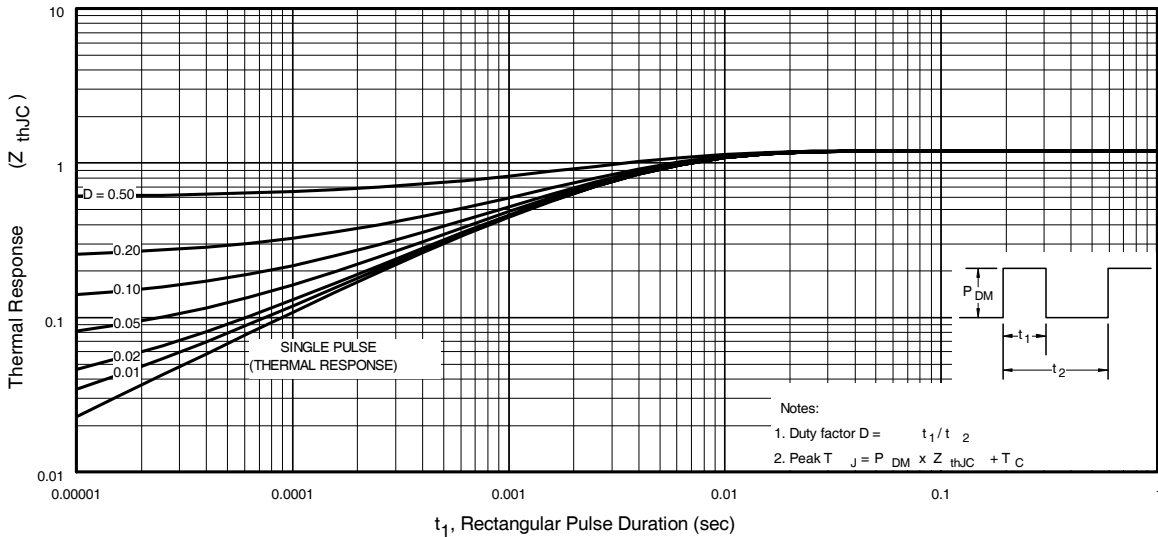
**Fig 9.** Maximum Drain Current Vs. Case Temperature



**Fig 10a.** Switching Time Test Circuit



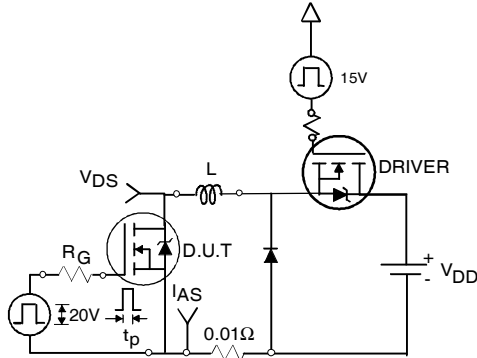
**Fig 10b.** Switching Time Waveforms



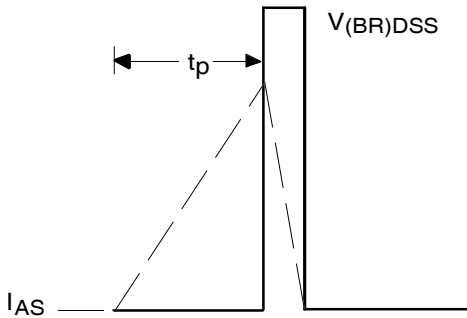
**Fig 11.** Maximum Effective Transient Thermal Impedance, Junction-to-Case

# IRFR/U3411PbF

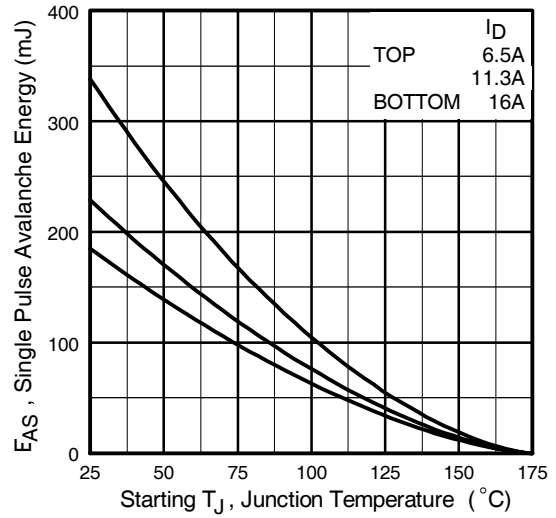
International  
**IR** Rectifier



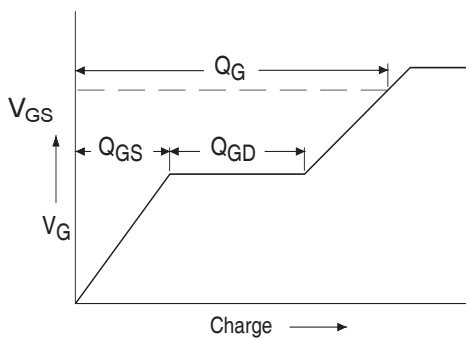
**Fig 12a.** Unclamped Inductive Test Circuit



**Fig 12b.** Unclamped Inductive Waveforms



**Fig 12c.** Maximum Avalanche Energy Vs. Drain Current



**Fig 13a.** Basic Gate Charge Waveform



**Fig 13b.** Gate Charge Test Circuit

Peak Diode Recovery dv/dt Test Circuit



\* Reverse Polarity of D.U.T for P-Channel



\*\*\*  $V_{GS} = 5.0V$  for Logic Level and 3V Drive Devices

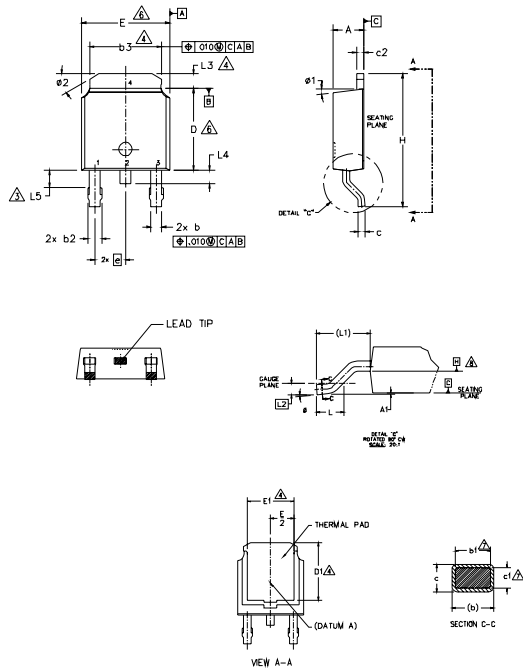
Fig 14. For N-channel HEXFET® power MOSFETs

# IRFR/U3411PbF

International  
**IR** Rectifier

## D-Pak (TO-252AA) Package Outline

Dimensions are shown in millimeters (inches)



**NOTES:**

- 1.- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
- 2.- DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS].
- 3.- LEAD DIMENSION UNCONTROLLED IN L5.
- 4.- DIMENSION D1, E1, L3 & b3 ESTABLISH A MINIMUM MOUNTING SURFACE FOR THERMAL PAD.
- 5.- SECTION C-C DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 AND 0.10 [0.13 AND 0.25] FROM THE LEAD TIP.
- 6.- DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005 [0.13] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
- 7.- DIMENSION b1 & c1 APPLIED TO BASE METAL ONLY.
- 8.- DATUM A & B TO BE DETERMINED AT DATUM PLANE H.
- 9.- OUTLINE CONFORMS TO JEDEC OUTLINE TO-252AA.

| SYMBOL | DIMENSIONS  |       |           |      | NOTES |
|--------|-------------|-------|-----------|------|-------|
|        | MILLIMETERS |       | INCHES    |      |       |
|        | MIN.        | MAX.  | MIN.      | MAX. |       |
| A      | 2.18        | 2.39  | .086      | .094 |       |
| A1     | -           | 0.13  | -         | .005 |       |
| b      | 0.64        | 0.89  | .025      | .035 | 7     |
| b1     | 0.65        | 0.79  | .025      | .031 |       |
| b2     | 0.76        | 1.14  | .030      | .045 | 4     |
| b3     | 4.95        | 5.46  | .195      | .215 |       |
| c      | 0.46        | 0.61  | .018      | .024 | 7     |
| c1     | 0.41        | 0.56  | .016      | .022 |       |
| c2     | 0.46        | 0.89  | .018      | .035 |       |
| D      | 5.97        | 6.22  | .235      | .245 | 6     |
| D1     | 5.21        | -     | .205      | -    | 4     |
| E      | 6.35        | 6.73  | .250      | .265 | 6     |
| E1     | 4.32        | -     | .170      | -    | 4     |
| e      | 2.29 BSC    |       | .090 BSC  |      |       |
| H      | 9.40        | 10.41 | .370      | .410 |       |
| L      | 1.40        | 1.78  | .055      | .070 |       |
| L1     | 2.74 BSC    |       | .108 REF. |      |       |
| L2     | 0.51 BSC    |       | .020 BSC  |      |       |
| L3     | 0.89        | 1.27  | .035      | .050 | 4     |
| L4     | -           | 1.02  | -         | .040 |       |
| L5     | 1.14        | 1.52  | .045      | .060 | 3     |
| e      | 0"          | 10"   | 0"        | 10"  |       |
| ø1     | 0"          | 15"   | 0"        | 15"  |       |
| ø2     | 25"         | 35"   | 25"       | 35"  |       |

**LEAD ASSIGNMENTS**

**HEXFEE T**

- 1.- GATE
- 2.- DRAIN
- 3.- SOURCE
- 4.- DRAIN

**IGBT & CoPAK**

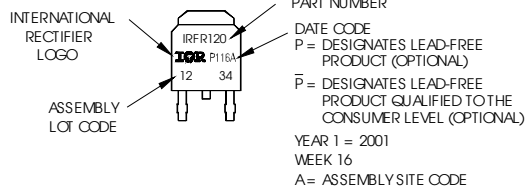
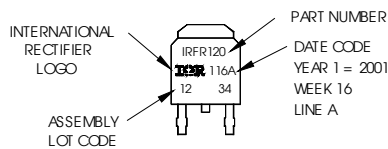
- 1.- GATE
- 2.- COLLECTOR
- 3.- EMITTER
- 4.- COLLECTOR

## D-Pak (TO-252AA) Part Marking Information

EXAMPLE: THIS IS AN IRFR120 WITH ASSEMBLY LOT CODE 1234 ASSEMBLED ON WW 16, 2001 IN THE ASSEMBLY LINE "A"

Note: "P" in assembly line position indicates "Lead-Free"

"P̄" in assembly line position indicates "Lead-Free" qualification to the consumer level



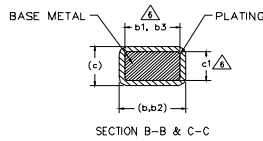
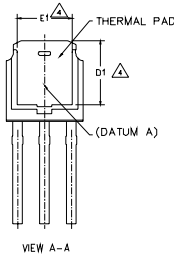
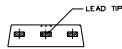
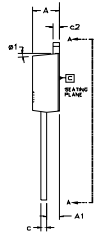
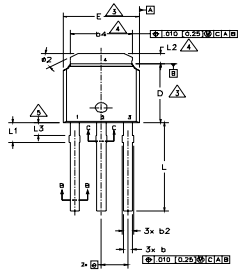
**Notes:**

1. For an Automotive Qualified version of this part please see <http://www.irf.com/product-info/auto/>
2. For the most current drawing please refer to IR website at <http://www.irf.com/package/>



## I-Pak (TO-251AA) Package Outline

Dimensions are shown in millimeters (inches)



- NOTES:
- 1.- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
  - 2.- DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS].
  - 3.- DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005 [0.13] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
  - 4.- THERMAL PAD CONTOUR OPTION WITHIN DIMENSION b4, L2, E1 & D1.
  - 5.- LEAD DIMENSION UNCONTROLLED IN L3.
  - 6.- DIMENSION b1, b3 & c1 APPLY TO BASE METAL ONLY.
  - 7.- OUTLINE CONFORMS TO JEDEC OUTLINE TO-251AA (Date 06/02).
  - 8.- CONTROLLING DIMENSION : INCHES.

| SYMBOL | DIMENSIONS  |      |          |      | NOTES |
|--------|-------------|------|----------|------|-------|
|        | MILLIMETERS |      | INCHES   |      |       |
|        | MIN.        | MAX. | MIN.     | MAX. |       |
| A      | 2.18        | 2.59 | .086     | .094 |       |
| A1     | 0.89        | 1.14 | .035     | .045 |       |
| b      | 0.64        | 0.89 | .025     | .035 |       |
| b1     | 0.65        | 0.79 | .025     | .031 | 6     |
| b2     | 0.76        | 1.14 | .030     | .045 |       |
| b3     | 0.76        | 1.04 | .030     | .041 | 6     |
| b4     | 4.95        | 5.46 | .195     | .215 | 4     |
| c      | 0.46        | 0.61 | .018     | .024 |       |
| c1     | 0.41        | 0.56 | .016     | .022 | 6     |
| c2     | 0.46        | 0.89 | .018     | .035 |       |
| D      | 5.97        | 6.22 | .235     | .245 | 3     |
| D1     | 5.21        | -    | .205     | -    | 4     |
| E      | 6.35        | 6.73 | .250     | .265 | 3     |
| E1     | 4.32        | -    | .170     | -    | 4     |
| e      | 2.29 BSC    |      | .090 BSC |      |       |
| L      | 8.89        | 9.65 | .350     | .380 |       |
| L1     | 1.91        | 2.29 | .045     | .090 |       |
| L2     | 0.89        | 1.27 | .035     | .050 | 4     |
| L3     | 1.14        | 1.52 | .045     | .060 | 5     |
| ø1     | 0"          | 15"  | 0"       | 15"  |       |
| ø2     | 25"         | 35"  | 25"      | 35"  |       |

LEAD ASSIGNMENTS

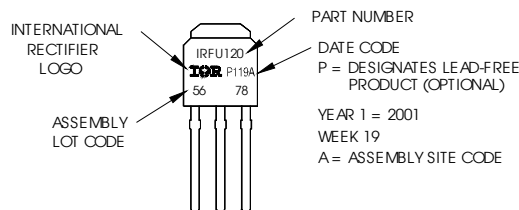
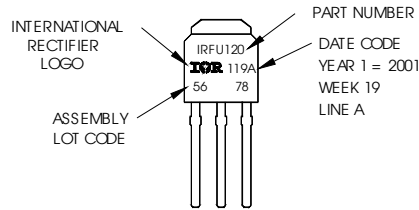
- HEXFET
- 1.- GATE
  - 2.- DRAIN
  - 3.- SOURCE
  - 4.- DRAIN

## I-Pak (TO-251AA) Part Marking Information

EXAMPLE: THIS IS AN IRFU120 WITH ASSEMBLY LOT CODE 5678 ASSEMBLED ON WW 19, 2001 IN THE ASSEMBLY LINE "A"

Note: "P" in assembly line position indicates Lead-Free

OR



Notes:

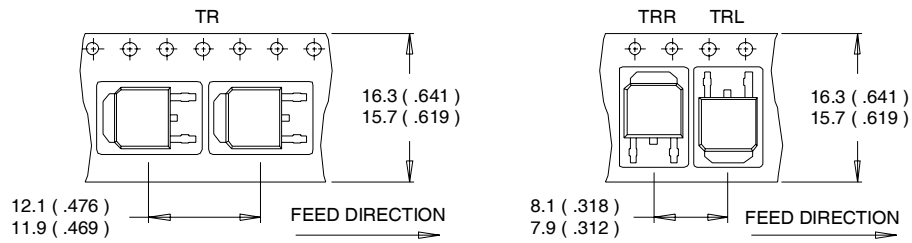
1. For an Automotive Qualified version of this part please see <http://www.irf.com/product-info/autof/>
2. For the most current drawing please refer to IR website at <http://www.irf.com/package/>

# IRFR/U3411PbF

International  
**IR** Rectifier

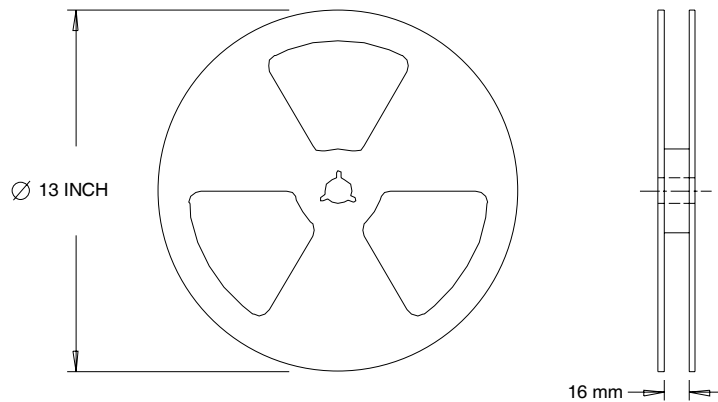
## D-Pak (TO-252AA) Tape & Reel Information

Dimensions are shown in millimeters (inches)



**NOTES :**

1. CONTROLLING DIMENSION : MILLIMETER.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS ( INCHES ).
3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



**NOTES :**

1. OUTLINE CONFORMS TO EIA-481.

Data and specifications subject to change without notice.  
This product has been designed and qualified for the Industrial market.  
Qualification Standards can be found on IR's Web site.

International  
**IR** Rectifier

**IR WORLD HEADQUARTERS:** 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105  
TAC Fax: (310) 252-7903

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[www.irf.com](http://www.irf.com)